ABSOLUTE MAXIMUM RATINGS

Vcc, IN to GND	0.3V to +6V
IN to V _C C	±0.3V
GND to PGND	±0.3V
All Other Pins to GND	$0.3V$ to $(V_{CC} + 0.3V)$
LX Current (Note 1)	±3.75A
REF Short Circuit to GND Duration	Continuous
ESD Protection	±2kV

Continuous Power Dissipation (T _A = +70°C) SSOP (derate 16.7mW/°C above +70°C;	
part mounted on 1 in.2 of 1oz. copper)	1.2W
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: LX has internal clamp diodes to PGND and IN. Applications that forward bias these diodes should take care not to exceed the IC's package power dissipation limits.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = V_{CC} = +3.3V, FBSEL = GND, T_A = 0^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage	VIN, VCC			3.0		5.5	V
			V _{IN} = V _{CC} = 4V to 5.5V, FBSEL = unconnected	3.300	3.333	3.366	
Preset Output Voltage	Vout	ILOAD = 0 to 2A, VFB = VOUT	VIN = VCC = 3V to 5.5V, FBSEL = VCC	2.500	2.525	2.550	V
		115 1001	VIN = VCC = 3V to 5.5V, FBSEL = REF	1.089	1.100	1.111	
Adjustable Output Voltage Range		V _{IN} = V _{CC} = 3V I _{LOAD} = 0, FBSE	to 5.5V, EL = GND or REF	V _{REF}		VIN	V
AC Load Degulation Error		FBSEL = GND			1		%
AC Load Regulation Error		FBSEL = REF, V	CC, or unconnected		2		70
DC Load Regulation Error		FBSEL = GND			0.2		%
DO LOAG NEGUIATION ENO		FBSEL = REF, V	FBSEL = REF, V _{CC} , or unconnected		0.4		/0
Dropout Voltage	V _{DO}	$V_{IN} = V_{CC} = 3V$	V _{IN} = V _{CC} = 3V, I _{LOAD} = 1A, FBSEL = V _{CC}			200	mV
Reference Voltage	V _{REF}				1.100	1.111	V
Reference Load Regulation	ΔV_{REF}	$I_{REF} = -1\mu A \text{ to } +10\mu A$			0.5	1	mV
PMOS Switch	Ron, p	I _L X = 0.5A	V _{IN} = 4.5V		70	150	mΩ
On-Resistance	HON, P	1LX = 0.5A	V _{IN} = 3V		100	200	11122
NMOS Switch	Ron, N	I _L x = 0.5A	VIN = 4.5V		70	150	mΩ
On-Resistance	TION, N	1LX = 0.0/1	VIN = 3V		100	200	11122
Current-Limit Threshold	ILIMIT			2.5	2.9	3.3	А
RMS LX Output Current						2.5	А
Idle Mode Current Threshold	I _{IM}			0.25	0.45	0.65	А
Switching Frequency	f	(Note 2)				350	kHz
No-Load Supply Current	I _{IN} + I _{CC}	V _{FB} = 1.2V			240	360	μΑ
Shutdown Supply Current	ICC(SHDN)	SHDN = GND			<1	3	μΑ
PMOS Switch Off-Leakage Current	I _{IN}	SHDN = GND				15	μA
Thermal Shutdown Threshold	T _{SHDN}	Hysteresis = 15°C			150		°C

2 /V|/1X|/VI

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{CC} = +3.3V, FBSEL = GND, T_A = 0^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Undervoltage Lockout Threshold	V _U VLO	V _{IN} falling, hysteresis = 40mV	2.5	2.6	2.7	V
FB Input Bias Current	I _{FB}	V _{FB} = 1.2V	0	80	200	nA
		$R_{TOFF} = 150k\Omega$	1.13	1.33	1.53	
Off-Time Default Period	toff	$R_{TOFF} = 30.1 k\Omega$	0.20	0.33		μs
		$R_{TOFF} = 499k\Omega$		4.3	5.6	
Off-Time Start-Up Period	toff	FB = GND		4 · toff		μs
On-Time Period	ton		0.4			μs
SS Source Current	Iss		3.5	5	6.5	μΑ
SS Sink Current	I _{SS}	V _{SS} = 1V	100			μΑ
SHDN Input Current	ISHDN	VSHDN = 0 to VCC	-0.5		0.5	μA
SHDN Input Low Threshold	VIL				0.8	V
SHDN Input High Threshold	V _{IH}		2.0			V
FBSEL Input Current			-5		+5	μΑ
		FBSEL = GND			0.2	
		FBSEL = REF	0.9		1.3	
FBSEL Logic Thresholds		FBSEL = unconnected	0.7 • V _C	0.	7 • Vcc + 0.2	V
		FBSEL = V _{CC}	V _{CC} - 0.2	2		
Maximum Output RMS Current					5.8	ARMS

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = V_{CC} = +3.3V, FBSEL = GND, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ (Note 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage	VIN			3.0		5.5	V
		ILOAD = 0 to 2A,	V _{IN} = V _{CC} = 4V to 5.5V, FBSEL = unconnected	3.276		3.390	- V
Preset Output Voltage	Vout	V _{FB} = V _{OUT}	$V_{IN} = 3V$ to 5.5V, FBSEL = V_{CC}	2.48		2.57	
			V _{IN} = 3V to 5.5V, FBSEL = REF	1.08		1.12	
Adjustable Output Voltage			V _{IN} = 3.0V to 5.5V, I _{LOAD} = 0, FBSEL = GND or REF			VIN	V
Reference Voltage	VREF					1.12	V
PMOS Switch	Ron, p	RON P $I_{LX} = 0.5A$ $V_{IN} = 4.$	V _{IN} = 4.5V			150	mΩ
On-Resistance	HON, P	ILX = 0.5A	VIN = 3V			200	11152
NMOS Switch	Ron. N	I _L x = 0.5A	$V_{IN} = 4.5V$			150	mΩ
On-Resistance	I TON, N	ILX = 0.5A	$V_{IN} = 3V$			200	11122
Current-Limit Threshold	ILIMIT			2.3		3.5	Α
Idle Mode Current Threshold	I _{IM}			0.2		0.7	А
No-Load Supply Current	I _{IN} + I _{CC}	V _{FB} = 1.2V				360	μΑ
FB Input Bias Current	I _{FB}	V _{FB} = 1.2V		0		250	nA
Off-Time Default Period	toff	$RTOFF = 150k\Omega$		1.03		1.63	μs

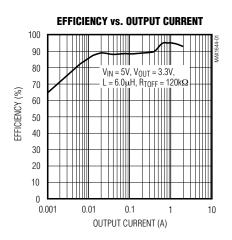
Note 2: Recommended operating frequency, not production tested.

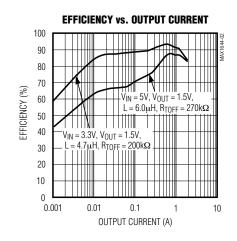
Note 3: Specifications from 0°C to -40°C are guaranteed by design, not production tested.

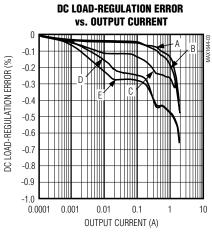


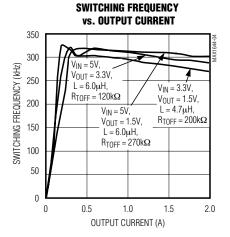
Typical Operating Characteristics

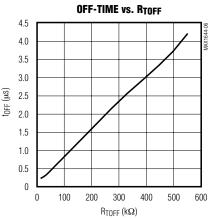
(Circuit of Figure 1, T_A = +25°C, unless otherwise noted.)

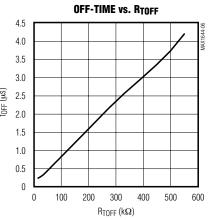


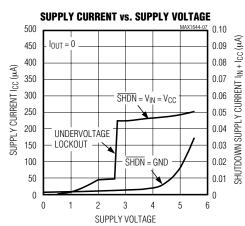


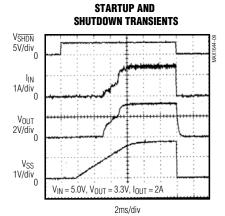








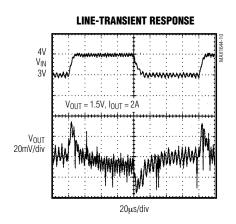


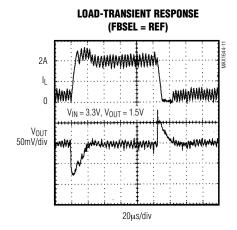


A: $V_{IN}=3.3V,~V_{OUT}=1.5V,~L=4.7\mu H,~R_{TOFF}=200k\Omega,~FBSEL=GND$ B: V_{IN} = 3.3V, V_{OUT} = 1.5V, L = 4.7 μ H, R_{TOFF} = 200k Ω , FBSEL = REF C: $V_{IN} = 5V$, $V_{OUT} = 3.3V$, $L = 6.0 \mu H$, $R_{TOFF} = 120 k \Omega$, FBSEL = OPEN D: V_{IN} = 5V, V_{OUT} = 1.5V, L = 6.0 μ H, $R_{TOFF} = 270k\Omega$, FBSEL = GNDE: V_{IN} = 5V, V_{OUT} = 1.5V, L = 6.0μH, R_{TOFF} = 270kΩ, FBSEL = REF

Typical Operating Characteristics (continued)

(Circuit of Figure 1, $T_A = +25$ °C, unless otherwise noted.)





Pin Description

PIN	NAME	FUNCTION
1	SHDN	Shutdown Control Input. Drive SHDN low to disable the reference, control circuitry, and internal MOSFETs. Drive high or connect to V _{CC} for normal operation.
2, 4	IN	Supply Voltage Input for the internal PMOS power switch
3, 14, 16	LX	Connection for the drains of the PMOS power switch and NMOS synchronous-rectifier switch. Connect the inductor from this node to output filter capacitor and load.
5	SS	Soft-Start. Connect a capacitor from SS to GND to limit inrush current during start-up.
6	COMP	Integrator Compensation. Connect a capacitor from COMP to V _{CC} for integrator compensation. See the <i>Integrator Amplifier</i> section.
7	TOFF	Off-Time Select Input. Sets the PMOS power switch off-time during constant-off-time operation. Connect a resistor from TOFF to GND to adjust the PMOS switch off-time.
8	FB	Feedback Input for both preset-output and adjustable-output operating modes. Connect directly to output for fixed-voltage operation or to a resistor-divider for adjustable operating modes.
9	GND	Analog Ground
10	REF	Reference Output. Bypass REF to GND with a 1µF capacitor.
11	FBSEL	Feedback Select Input. Selects AC load-regulation error and output voltage. See Table 2 for programming instructions.
12	Vcc	Analog Supply Voltage Input. Supplies internal analog circuitry. Bypass VCC with a 10Ω and $2.2\mu F$ low-pass filter. See Figure 1.
13, 15	PGND	Power Ground. Internally connected to the internal NMOS synchronous-rectifier switch.



Detailed Description

The MAX1644 synchronous, current-mode, constant-off-time, PWM DC-DC converter steps down input voltages of +3V to +5.5V to a preset output voltage of either +3.3V or +2.5V, or to an adjustable output voltage from +1.1V to V_{IN}. The device delivers up to 2A of continuous load current. Internal switches composed of a 0.1 Ω PMOS power switch and a 0.1 Ω NMOS synchronous-rectifier switch improve efficiency, reduce component count, and eliminate the need for an external Schottky diode.

The MAX1644 optimizes performance by operating in constant-off-time mode under heavy loads and in Maxim's proprietary Idle Mode under light loads. A single resistor-programmable constant-off-time control sets switching frequencies up to 350kHz, allowing the user to optimize performance trade-offs in efficiency, switching noise, component size, and cost. Under low-dropout conditions, the device operates in a 100% duty-cycle mode, where the PMOS switch remains permanently on. Idle Mode enhances light-load efficiency by skipping cycles, thus reducing transition and gatecharge losses.

When power is drawn from a regulated supply, constantoff-time PWM architecture essentially provides constantfrequency operation. This architecture has the inherent advantage of quick response to line and load transients.

The MAX1644's current-mode, constant-off-time PWM architecture regulates the output voltage by changing the PMOS switch on-time relative to the constant off-time. Increasing the on-time increases the peak inductor current and the amount of energy transferred to the load per pulse.

Modes of Operation

The current through the PMOS switch determines the mode of operation: constant-off-time mode (for load currents greater than 0.2A) or Idle Mode (for load currents less than 0.2A). Current sense is achieved through a proprietary architecture that eliminates current-sensing $\rm I^2R$ losses.

Constant-Off-Time Mode

Constant-off-time operation occurs when the current through the PMOS switch is greater than the Idle Mode threshold current (0.4A, which corresponds to a load current of 0.2A). In this mode, the regulation comparator turns the PMOS switch on at the end of each off-time, keeping the device in continuous-conduction mode. The PMOS switch remains on until the output is in regulation or the current limit is reached. When the PMOS switch turns off, it remains off for the pro-

grammed off-time (toff). If the output falls dramatically out of regulation—approximately VFB / 4—the PMOS switch remains off for approximately four times toff. The NMOS synchronous rectifier turns on shortly after the PMOS switch turns off, and it remains on until shortly before the PMOS switch turns back on.

Idle Mode

Under light loads, the device improves efficiency by switching to a pulse-skipping Idle Mode. Idle Mode operation occurs when the current through the PMOS switch is less than the Idle Mode threshold current. Idle Mode forces the PMOS to remain on until the current through the switch reaches 0.4A, thus minimizing the unnecessary switching that degrades efficiency under light loads. In Idle Mode, the device operates in discontinuous conduction. Current-sense circuitry monitors the current through the NMOS synchronous switch, turning it off before the current reverses. This prevents current from being pulled from the output filter through the inductor and NMOS switch to ground. As the device switches between operating modes, no major shift in circuit behavior occurs.

100% Duty-Cycle Operation

When the input voltage drops near the output voltage, the duty cycle increases until the PMOS MOSFET is on continuously. The dropout voltage in 100% duty cycle is the output current multiplied by the on-resistance of the internal PMOS switch and parasitic resistance in the inductor. The PMOS switch remains on continuously as long as the current limit is not reached.

Shutdown

Drive \overline{SHDN} to a logic-level low to place the MAX1644 in low-power shutdown mode and reduce supply current to less than 1µA. In shutdown, all circuitry and internal MOSFETs turn off, and the LX node becomes high impedance. Drive \overline{SHDN} to a logic-level high or connect to VCC for normal operation.

Summing Comparator

Three signals are added together at the input of the summing comparator (Figure 1): an output voltage error signal relative to the reference voltage, an integrated output voltage error correction signal, and the sensed PMOS switch current. The integrated error signal is provided by a transconductance amplifier with an external capacitor at COMP. This integrator provides high DC accuracy without the need for a high-gain amplifier. Connecting a capacitor at COMP modifies the overall loop response (see the *Integrator Amplifier* section).

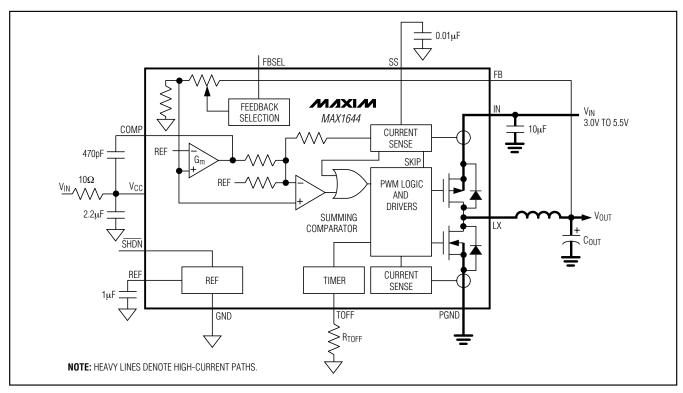


Figure 1. Functional Diagram

Synchronous Rectification

In a step-down regulator without synchronous rectification, an external Schottky diode provides a path for current to flow when the inductor is discharging. Replacing the Schottky diode with a low-resistance NMOS synchronous switch reduces conduction losses and improves efficiency.

The NMOS synchronous-rectifier switch turns on following a short delay after the PMOS power switch turns off, thus preventing cross conduction or "shoot through." In constant-off-time mode, the synchronous-rectifier switch turns off just prior to the PMOS power switch turning on. While both switches are off, inductor current flows through the internal body diode of the NMOS switch. The internal body diode's forward voltage is relatively high.

Thermal Resistance

Junction-to-ambient thermal resistance, θ_{JA} , is highly dependent on the amount of copper area immediately surrounding the IC leads. The MAX1644 evaluation kit has 0.5 in.² of copper area and a thermal resistance of 60°C/W with no airflow. Airflow over the IC significantly reduces the junction-to-ambient thermal resistance. For

heatsinking purposes, evenly distribute the copper area connected at the IC among the high-current pins.

Power Dissipation

Power dissipation in the MAX1644 is dominated by conduction losses in the two internal power switches. Power dissipation due to supply current in the control section and average current used to charge and discharge the gate capacitance of the internal switches are less than 30mW at 300kHz. This number is reduced when the switching frequency decreases as the part enters Idle Mode. Combined conduction losses in the two power switches are approximated by:

$$PD = IOUT^2 \cdot RON$$

The junction-to-ambient thermal resistance required to dissipate this amount of power is calculated by:

$$\theta_{JA} = (T_{J,MAX} - T_{A,MAX}) / P_{D}$$

where: θ_{JA} = junction-to-ambient thermal resistance

TJ.MAX = maximum junction temperature

TA.MAX = maximum ambient temperature

Design Procedure

For typical applications, use the recommended component values in Table 1. For other applications, take the following steps:

- 1) Select the desired PWM-mode switching frequency; 300kHz is a good starting point.
- 2) Select the constant-off-time as a function of input voltage, output voltage, and switching frequency.
- 3) Select RTOFF as a function of off-time.
- 4) Select the inductor as a function of output voltage, off-time, and peak-to-peak inductor current.

Table 1. Recommended Component Values (IOUT = 2A, fPWM = 300kHz)

V _{IN} (V)	V _{OUT} (V)	L (μH)	R _{TOFF} (kΩ)
5	3.3	6.0	120
5	2.5	6.8	180
5	1.8	6.8	240
5	1.5	6.0	270
3.3	2.5	3.3	82
3.3	1.8	4.7	180
3.3	1.5	4.7	200

Table 2. Output Voltage and AC Load-Regulation Selection

PI	N	OUTPUT VOLTAGE	AC LOAD- REGULATION		
FBSEL	SSEL FB		ERROR (%)		
Vcc	Output Voltage	2.5	2		
Unconnected	Output Voltage	3.3	2		
REF	Resistor Divider	Adjustable	2		
GND	Resistor Divider	Adjustable	1		

Setting the Output Voltage

The output of the MAX1644 is selectable between one of two preset output voltages: (2.5V or 3.3V) with a 2% AC load-regulation error, or an adjustable output voltage from the reference voltage (nominally 1.1V) up to VIN with a 1% or 2% AC load-regulation error. For a preset output voltage, connect FB to the output voltage, and connect FBSEL to VCC (2.5V output voltage) or

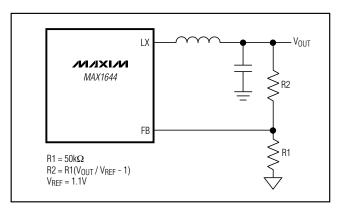


Figure 2. Adjustable Output Voltage

leave unconnected (3.3V output voltage). Internal resistor-dividers divide down the output voltage, regulating the divided voltage to the internal reference voltage. For output voltages other than 2.5V or 3.3V, or for tighter AC load regulation, connect FBSEL to GND (1% regulation) or to REF (2% regulation), and connect FB to a resistor divider between the output voltage and ground (Figure 2). Regulation is maintained for adjustable output voltages when VFB equals VREF. Use $50 \mathrm{k} \Omega$ for R1. R2 is given by the equation:

$$R2 = R1 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

where V_{REF} is typically 1.1V.

Programming the Switching Frequency and Off-Time

The MAX1644 features a programmable PWM mode switching frequency, which is set by the input and output voltage and the value of RTOFF, connected from TOFF to GND. RTOFF sets the PMOS power switch off-time in PWM mode. Use the following equation to select the off-time according to your desired switching frequency in PWM mode (IOUT > 0.2A):

$$t_{OFF} = \frac{\left(V_{IN} - V_{OUT} - V_{PMOS}\right)}{f_{PWM}\left(V_{IN} - V_{PMOS} + V_{NMOS}\right)}$$

where: toff = the programmed off-time

V_{IN} = the input voltage V_{OUT} = the output voltage

V_{NMOS} = the voltage drop across the internal

PMOS power switch

Mos = the voltage drop across the in

V_{PMOS} = the voltage drop across the internal NMOS synchronous-rectifier switch

 $f_{PWM} = switching frequency in PWM mode (I_{OUT} > 0.2A)$

Select RTOFF according to the formula:

RTOFF = $(tOFF - 0.07\mu s) (150k\Omega / 1.26\mu s)$

Recommended values for R_{TOFF} range from $39k\Omega$ to $470k\Omega$ for off-times of 0.4µs to 4µs.

Inductor Selection

Three key inductor parameters must be specified: inductor value (L), peak current (IPEAK), and DC resistance (RDC). The following equation includes a constant, denoted as LIR, which is the ratio of peak-to-peak inductor AC current (ripple current) to maximum DC load current. A higher value of LIR allows smaller inductance but results in higher losses and ripple. A good compromise between size and losses is found at approximately a 25% ripple-current to load-current ratio (LIR = 0.25), which corresponds to a peak inductor current 1.125 times higher than the DC load current:

$$L = \frac{V_{OUT} \times t_{OFF}}{I_{OUT} \times LIR}$$

where: IOUT = maximum DC load current

LIR = ratio of peak-to-peak AC inductor current to DC load current, typically 0.25

The peak inductor current at full load is $1.125 \cdot I_{OUT}$ if the above equation is used; otherwise, the peak current is calculated by:

$$I_{PEAK} = I_{OUT} + \frac{V_{OUT} \times t_{OFF}}{2 \times L}$$

Choose an inductor with a saturation current at least as high as the peak inductor current. To minimize loss, choose an inductor with a low DC resistance.

Capacitor Selection

The input filter capacitor reduces peak currents and noise at the voltage source. Use a low-ESR and low-ESL capacitor located no further than 5mm from IN. Select the input capacitor according to the RMS input ripple-current requirements and voltage rating:

$$I_{RIPPLE} = I_{LOAD} \frac{\sqrt{V_{OUT}(V_{IN} - V_{OUT})}}{V_{IN}}$$

The output filter capacitor affects the output voltage ripple, output load-transient response, and feedback loop stability. For stable operation, the MAX1644 requires a minimum output ripple voltage of VRIPPLE ≥ 2% • VOUT (with 2% load regulation setting).

The minimum ESR of the output capacitor should be:

$$ESR > 1\% \times \frac{L}{t_{OFF}}$$

Stable operation requires the correct output filter capacitor. When choosing the output capacitor, ensure that:

Cout
$$\geq$$
 (toff / Vout) \times (64 μ FV / μ s)

With an AC load regulation setting of 1%, the COUT requirement doubles, and the minimum ESR of the output capacitor is halved.

Integrator Amplifier

An internal transconductance amplifier fine tunes the output DC accuracy. A capacitor, C_{COMP}, from COMP to V_{CC} compensates the transconductance amplifier. For stability, choose:

A large capacitor value maintains a constant average output voltage but slows the loop response to changes in output voltage. A small capacitor value speeds up the loop response to changes in output voltage but decreases stability. Choose the capacitor values that result in optimal performance.

Setting the AC Loop Gain

The MAX1644 allows selection of a 1% or 2% AC load-regulation error when the adjustable output voltage mode is selected (Table 2). A 2% setting is automatically selected in preset output voltage mode (FBSEL connected to VCC or unconnected). A 2% load-regulation error setting reduces output filter capacitor requirements, allowing the use of smaller and less expensive capacitors. Selecting a 1% load-regulation error reduces transient load errors, but requires larger capacitors.

Soft-Start

Soft-start allows a gradual increase of the internal current limit to reduce input surge currents at start-up and at exit from shutdown. A charging capacitor, Css, placed from SS to GND sets the rate at which the internal current limit is changed. Upon power-up, when the device comes out of undervoltage lockout (2.6V typ) or after the SHDN pin is pulled high, a 5µA constant-current source charges the soft-start capacitor and the voltage on SS increases. When the voltage on SS is less than approximately 0.7V, the current limit is set to zero. As the voltage increases from 0.7V to approximately 1.8V, the current limit is adjusted from 0 to 2.9A. The voltage across the soft-start capacitor changes with time according to the equation:

$$V_{SS} = \frac{5\mu A \times t}{C_{SS}}$$

The soft-start current limit varies with the voltage on the soft-start pin, SS, according to the equation:

$$ILIMIT = (VSS - 0.7V) \cdot 2.7A/V$$
, for $VSS > 0.7V$

The constant-current source stops charging once the voltage across the soft-start capacitor reaches 1.8V (Figure 3).

Circuit Layout and Grounding

Good layout is necessary to achieve the MAX1644's intended output power level, high efficiency, and low noise. Good layout includes the use of a ground plane, appropriate component placement, and correct routing of traces using appropriate trace widths. The following points are in order of decreasing importance:

1) Minimize switched-current and high-current ground loops. Connect the input capacitor's ground, the output capacitor's ground, and PGND together.

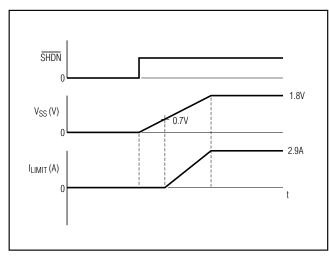


Figure 3. Soft-Start Current Limit over Time

- 2) Connect the input filter capacitor less than 5mm away from IN. The connecting copper trace carries large currents and must be at least 2mm wide, preferably 5mm.
- 3) Place the LX node components as close together and as near to the device as possible. This reduces resistive and switching losses as well as noise.
- 4) A ground plane is essential for optimum performance. In most applications, the circuit is located on a multilayer board, and full use of the four or more layers is recommended. Use the top and bottom layers for interconnections and the inner layers for an uninterrupted ground plane.

Chip Information

TRANSISTOR COUNT: 1758

Package Information

Ν

14L

16L

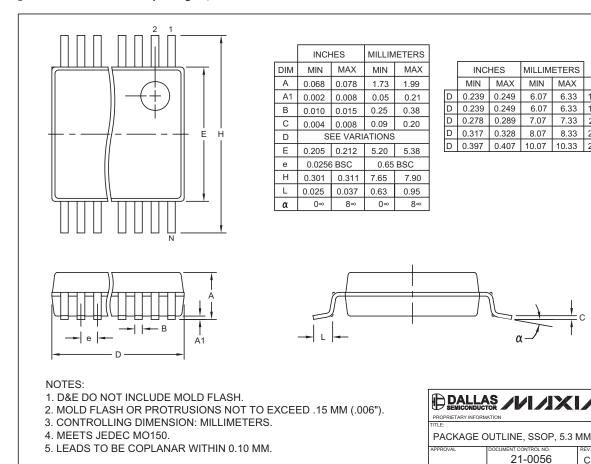
20L

24L

28L

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(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



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